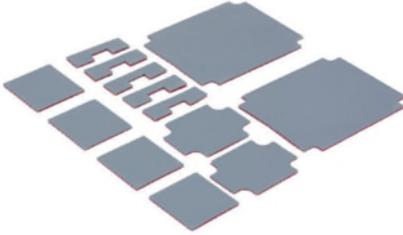


PRODUCT DESCRIPTION



Tflex™ SF800 is a high-performance, compliant, silicone free thermal interface material. By coupling extremely high thermal conductivity with exceptional wetting characteristics, Tflex™ SF800 provides some of the lowest thermal resistance values in the industry. This makes it well-suited for applications where silicone based pads are traditionally used as well as those applications which are silicone sensitive.

Tflex™ SF800 is naturally tacky on both sides requiring no additional adhesive coating, which would inhibit thermal performance. The natural tack allows for the pad to be held in place during assembly.

FEATURES AND BENEFITS

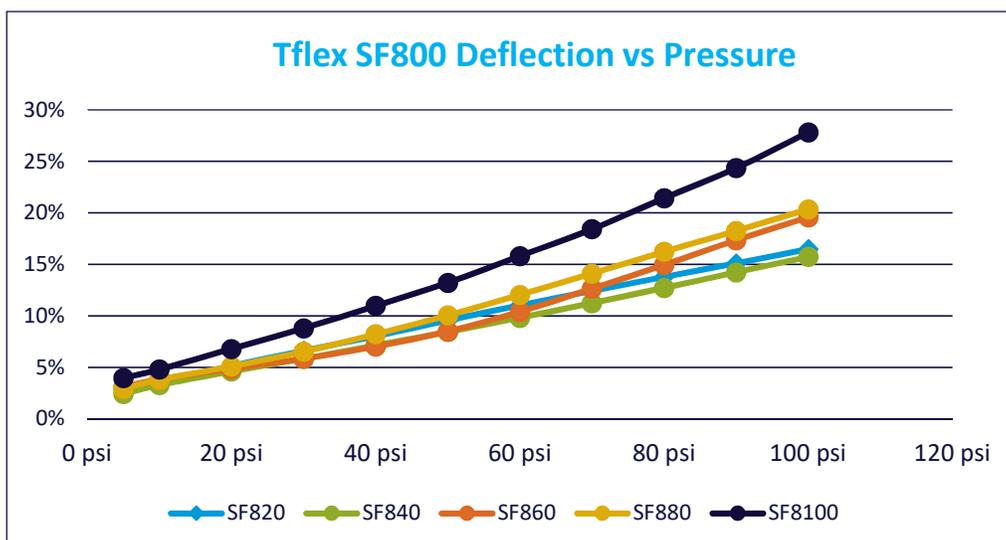
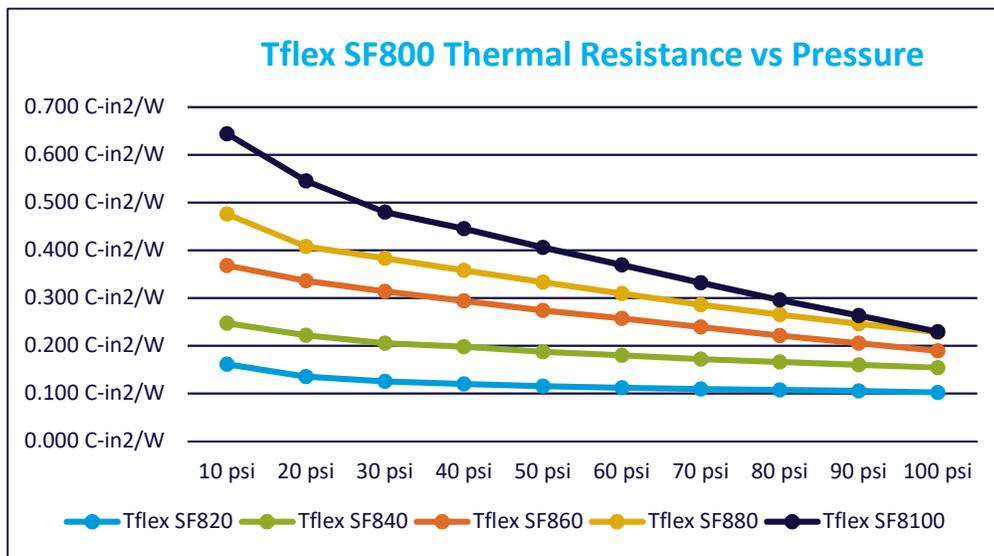
- Silicone-free gap filler
- Thermal Conductivity of 7.8 W/mK
- Exceptionally low thermal resistance
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

SPECIFICATIONS

PROPERTIES	TYPICAL VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone free sheet	N/A
Color	Grey	Visual
Thickness Range	0.50mm (0.020") 4.0mm (0.16")	N/A
Thermal Conductivity (W/mK)	7.8	ASTM D5470
Density (g/cc)	3.21	Helium Pycnometer
Hardness (Shore 00)	81	ASTM D2240
Weight Loss over time @ 120°C, 168 hrs (%)	< 0.2	TGA
Temperature Range	-25°C to 120°C	Laird Test Method
Rth@ 40 mils, 10 psi	0.237 °C-in ² /W	ASTM D5470 (Modified)
Dielectric Constant @ 1 MHz	16	ASTM D150
UL Flammability Rating	V-0	UL 94
Volume Resistivity	5 x 10 ¹² ohm-cm	ASTM D257



Tflex™ SF800 Series Silicone Free Thermal Gap Filler



AVAILABILITY

STANDARD THICKNESSES

- 0.5mm (0.020") to 4.0mm (0.160") thick material available in 0.25mm (0.010") increments
- Available in standard sheet sizes of 9" x 9" or custom die cut parts

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. SF8xxx indicates Tflex SF800 product line with thickness in mils (0.001")

EXAMPLES:

- Tflex™ SF840 = 0.040" thick Tflex™ SF800 material

Tflex SF800 DS 041519

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